

#### **ATTENTION**

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

#### **Features**

- •Super high flux output and high luminance.
- •Designed for high current operation.
- •Low thermal resistance.
- •Low voltage DC operated.
- Superior ESD protection.
- ●Package: 500pcs/reel.
- Not reflow compatible.
- •The component is internally protected with silicone gel.
- ●RoHS compliant.

#### **Application Note**

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

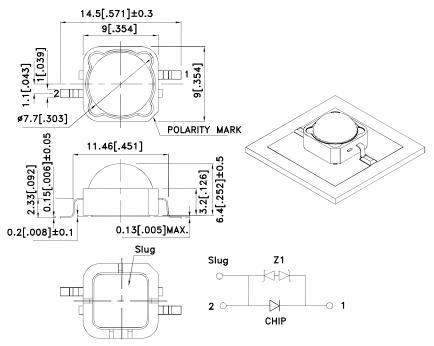
#### Part Number: AAD1-9090QB10ZC BLUE



#### **Applications**

- traffic signaling.
- backlighting (illuminated advertising, general lighting).
- interior and exterior automotive lighting.
- substitution of micro incandescent lamps.
- portable light source (e.g. bicycle flashlight).
- signal and symbol luminaire for orientation.
- marker lights (e.g. steps, exit ways, etc).
- decorative and entertainment lighting.
- indoor and outdoor commercial and residential architectural lighting.

#### **Package Dimensions**



#### Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.





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 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: C.H.HAN
 ERP: 1201200213

#### **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

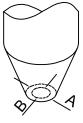




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.





5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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#### Selection Guide

| Part No.        | Dice           | Lens Type   | luminous Intensity [2]<br>lv(cd)@ 350mA |      | Φν (lm) [2]<br>@ 350mA |      | Viewing<br>Angle [1] |
|-----------------|----------------|-------------|---|------|------------------------|------|----------------------|
|                 |                |             | Min.                                    | Тур. | Min.                   | Тур. | 201/2                |
| AAD1-9090QB10ZC | BLUE (AlGaInN) | Water Clear | 3.6                                     | 5    | 17                     | 24   | 100°                 |

#### Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

#### Absolute Maximum Ratings at Ta=25°C

| Parameter                               | Symbol              | Value       | Unit |  |  |
|---|---------------------|-------------|------|--|--|
| Power dissipation                       | PD                  | 1.25        | W    |  |  |
| Junction temperature                    | TJ                  | 110         | °C   |  |  |
| Reverse Voltage                         | Vr                  | 5           | V    |  |  |
| Operating Temperature                   | Тор                 | -40 To +100 | °C   |  |  |
| Storage Temperature                     | Tstg                | -40 To +100 | °C   |  |  |
| DC Forward Current [1]                  | lF                  | 350         | mA   |  |  |
| Peak Forward Current [2]                | Іғм                 | 500         | mA   |  |  |
| Thermal resistance [1]                  | Rth j-slug          | 9           | °C/W |  |  |
| Electrostatic Discharge Threshold (HBM) |                     | 8000        | V    |  |  |
| Iron Soldering [3]                      | 350°C For 3 Seconds |             |      |  |  |

#### Notes:

- 1. Results from mounting on MCPCB.
- 2. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 3.1.29mm distance from solder joint to package.

#### Electrical / Optical Characteristics at T<sub>A</sub>=25°C

| Parameter  | Symbol         | Value | Unit  |
|--|----------------|-------|-------|
| Wavelength at peak emission Ir=350mA [Typ.]                                      | λpeak          | 452   | nm    |
| Dominant Wavelength Ir=350mA [Typ.]  | λ dom [1]      | 458   | nm    |
| Spectral bandwidth at 50%ΦREL MAX IF=350mA [Typ.]                                | Δλ             | 20    | nm    |
| Allowable Reverse Current [Max.]   | l <sub>R</sub> | 85    | mA    |
| Forward Voltage Ir=350mA [Min.]  |                | 2.8   |       |
| Forward Voltage Ir=350mA [Typ.]  | VF [2]         | 3.2   | V     |
| Forward Voltage IF=350mA [Max.]  |                | 3.6   |       |
| Temperature coefficient of λpeak<br>I <sub>F</sub> =350mA, -10°C≤ T≤100°C [Typ.] | TCλpeak        | 0.2   | nm/°C |
| Temperature coefficient of λdom Ir=350mA, -10°C≤ T≤100°C [Typ.]                  | TCλdom         | 0.1   | nm/°C |
| Temperature coefficient of VF IF=350mA, -10°C≤ T≤100°C [Typ.]                    | TCv            | -3.2  | mV/°C |

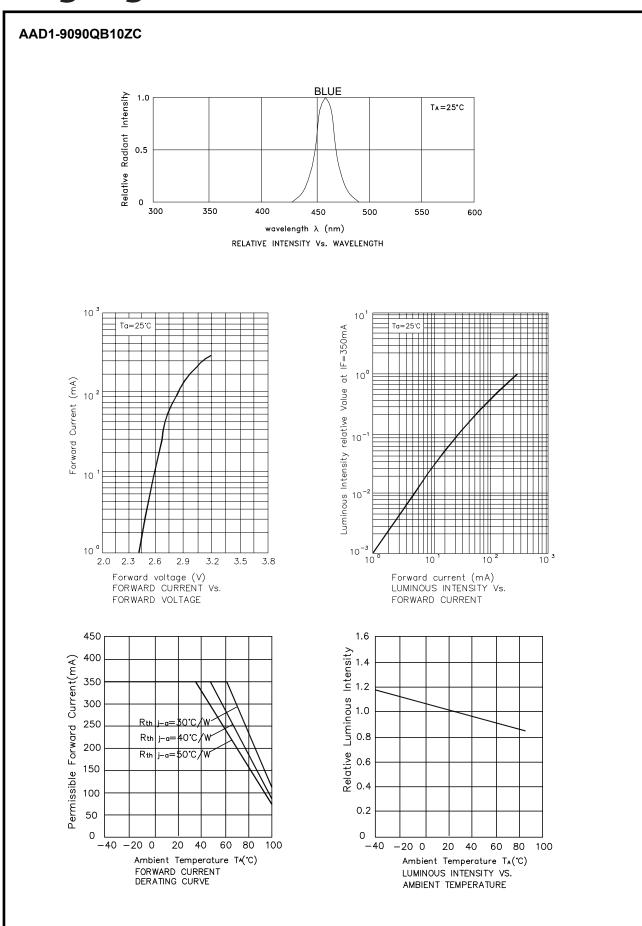
#### Notes

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

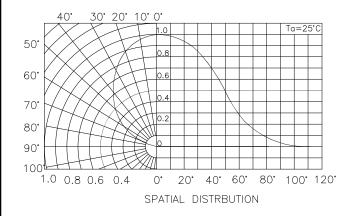
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<sup>2.</sup> Luminous intensity / luminous flux: +/-15%.

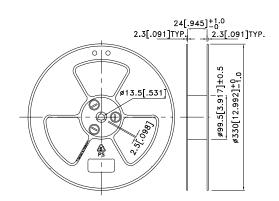


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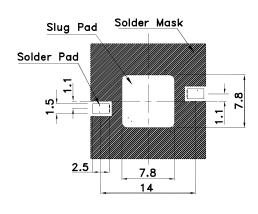
#### AAD1-9090QB10ZC

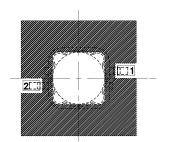


#### **Reel Dimension**



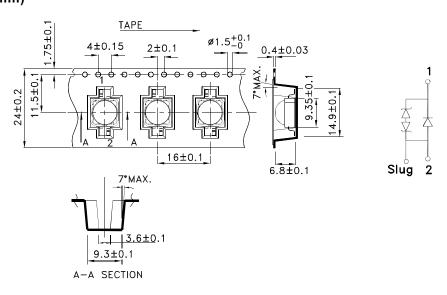
### Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)



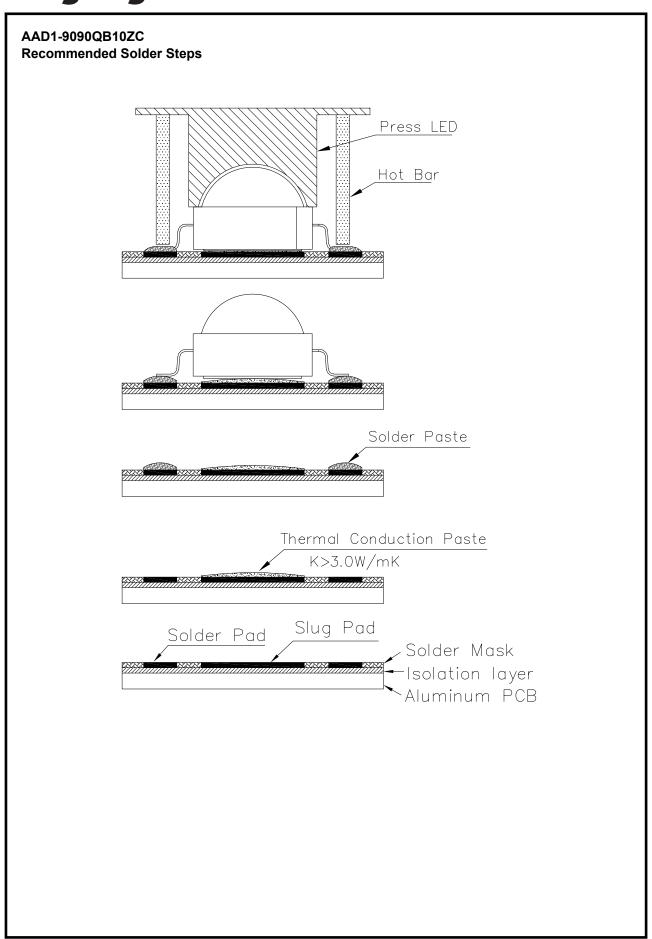


### Tape Specifications

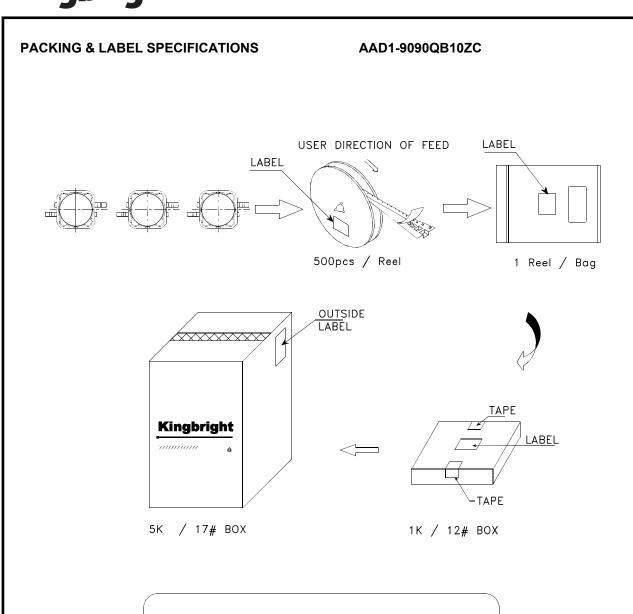
(Units : mm)



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